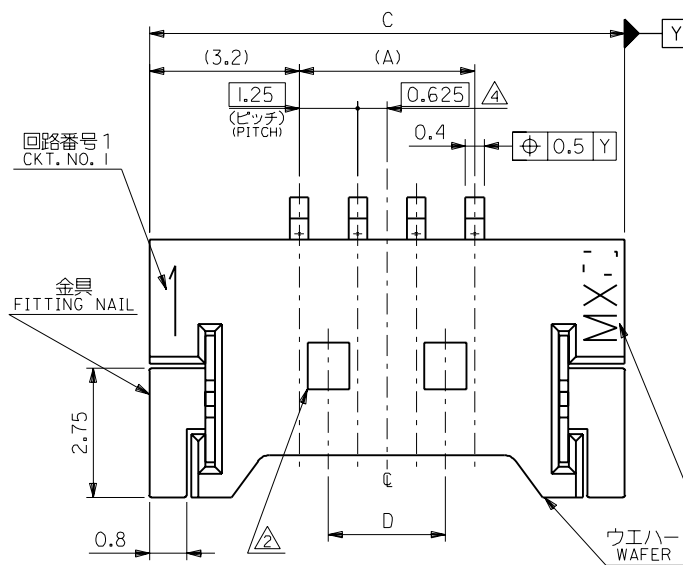
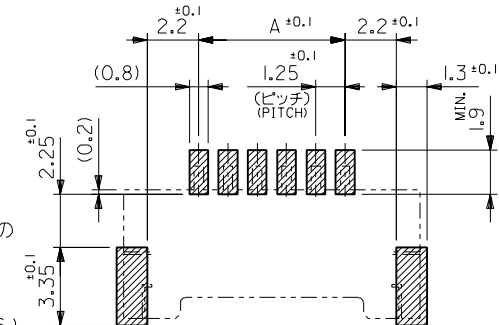




注記 NOTES

1. 嵌合相手: 51146 シリーズ
MATES WITH: 51146 SERIES
△ ロック窓は2、3極品は1箇所、4極品以上は2箇所とする。
LOCKING WINDOW: ONE PLACE FOR 2 AND 3 CIRCUIT PRODUCTS AND TWO PLACES FOR MORE THAN 3 CIRCUIT PRODUCTS.
△ 基準面 [V] からのソルダーテールと金具の半田付け面のズレ量は、
上方に 0.05MAX. 下方に 0.15MAX. とし、20 極以下の相互のバラツキ量は 0.1MAX. とする。
MISALIGNMENT OF SOLDER TAIL AND FITTING NAIL FROM [V]
: UPPER DIRECTION 0.05MAX.
: LOWER DIRECTION 0.15MAX.
: OFFSET BETWEEN UPPER AND LOWER 0.1MAX. (UNDER 20 CKTS.)
△ 偶数極の製品に適用。
APPLY EVEN CIRCUIT PRODUCTS.
5. 材質 MATERIAL
ウエハー WAFER: PPHS, UL94V-0
ピン: リン青銅 (コンタクト部: 金メッキ、テール部: 半田メッキ)
PIN: PHOS-BRO (CONTACT: Au PLATING, TAIL: Sn-Pb PLATING)
金具: リン青銅 (半田メッキ)
FITTING NAIL: PHOS-BRO (Sn-Pb PLATING)

トレードマーク
TRADE MARK

参考基板レイアウト

RECOMMENDED P.C. BOARD PATTERN DIM. (REF.)

8.75	22.5	30.15	26.27	23.75	53780-2010	20
7.5	20	27.65	23.77	21.25	↑ -1810	18
6.25	17.5	25.15	21.27	18.75	↑ -1610	16
6.25	16.25	23.9	20.02	17.5	↑ -1510	15
5	15	22.65	18.77	16.25	↑ -1410	14
3.75	12.5	20.15	16.27	13.75	↑ -1210	12
2.5	10	17.65	13.77	11.25	↑ -1010	10
2.5	8.75	16.4	12.52	10	↑ -0910	9
1.25	7.5	15.15	11.27	8.75	↑ -0810	8
1.25	6.25	13.9	10.02	7.5	↑ -0710	7
—	5	12.65	8.77	6.25	↑ -0610	6
—	3.75	11.4	7.52	5	↑ -0510	5
—	2.5	10.15	6.27	3.75	↑ -0410	4
—	—	8.9	5.02	2.5	↑ -0310	3
—	—	7.65	3.77	1.25	↑ -0210	2
E	D	C	B	A	ENG. NO.	CKT. 極数

G	変更 REVISED	(JC2000-0862)	S.M.	T.Y	'00/6/21
F	変更 REVISED	(JC80823)	S.M.	S.K	'98/4/22
E	変更 REVISED	(JC70644)	S.M.	Y.M	'91/1/27
D	変更 REVISED	(JC70592)	S.M.	Y.M	'91/1/3
C	変更 REVISED	(JC70159)	S.M.	Y.M	'96/8/9
B	変更 REVISED	(JC60804)	S.M.	M.F	'96/5/1
A	変更 REVISED	(JC60541)	S.M.	H.H	'96/2/6
O	新規作成 PROPOSED	(JC60428)	Y.M	H.H	'95/12/25
記号 LTR	変更内容 REVISION RECORD	DR.	日付 DATE	CHK.	尺度 SCALE

角度 ANGLE	±3°
30 以上 OVER	±0.3
10 以上 30 未満 UNDER	±0.25
10 未満 UNDER	±0.2
般公差 GENERAL TOLERANCES	

材料 MATERIAL	注記参照 SEE NOTES
仕上げ FINISH	—
適用電線範囲 WIRE RANGE	—
被覆外径 INS. RANGE	—
DRAWN BY '95/12/25 Y. MIZUNO	CHK'D BY '00/6/21 T. YAMAGUCHI
APP'D BY '00/6/21 M. FUKUSHIMA	尺度 SCALE

MOLEX-JAPAN CO., LTD. 日本モレックス株式会社
REVISE ONLY ON CAD SYSTEM
TITLE 名称
1.25 WIRE TO BOARD CONN. WAFER ASS'Y FOR S.M.T.
DWG. NO. (SHEET 1 OF 2) REV
SD-53780-***10
G

DWG. NO.
SD-53780-**-10

E

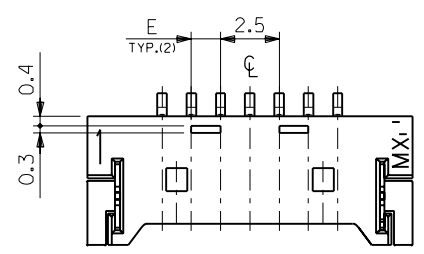
D

C

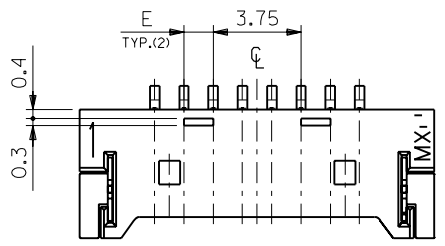
B

A

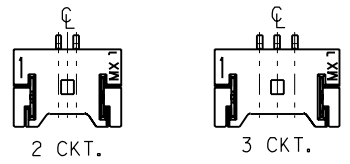
ALL DIMENSIONS IN METRIC DO NOT SCALE DRAWING



7~19極の奇数極に適用
APPLY FOR ODD CIRCUITS OF 7~19



8~20極の偶数極に適用
APPLY FOR EVEN CIRCUITS OF 8~20



ロック形状図
LOCK CONFIGURATION

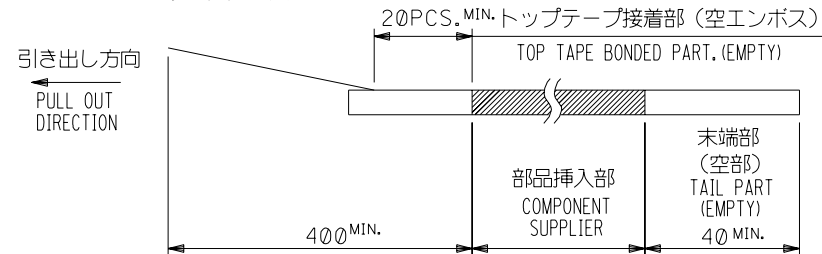
G 変更 REVISED (JC2000-0862)		S.M.	T.Y.	'00/6/21	材料 MATERIAL 注記参照 SEE NOTES	moLEX MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社
F 変更 REVISED (JC800823)		S.M.	S.K.	'98/4/22		
E 変更 REVISED (JC70644)		S.M.	Y.M.	'97/1/27	仕上げ FINISH —#—	REVISE ONLY ON CAD SYSTEM
D 変更 REVISED (JC70592)		S.M.	Y.M.	'97/1/3		
C 変更 REVISED (JC70159)		S.M.	Y.M.	'96/8/9	適用電線範囲 WIRE RANGE —#—	TITLE 名称 I.25 WIRE TO BOARD CONN. WAFER ASS'Y FOR S.M.T.
B 変更 REVISED (JC60804)		S.M.	M.F.	'96/5/1		
A 変更 REVISED (JC60541)		S.M.	H.H.	'96/2/6	被覆外径 INS. RANGE —#—	DRAWN BY '95/12/25 Y.MIZUNO CHK'D BY '00/6/21 T.YAMAGUCHI
O 新規作成 PROPOSED (JC60428)		Y.M.	H.H.	'95/12/25		
一般公差 GENERAL TOLERANCES		記号 LTR	変更内容 REVISION RECORD	DR. CHK.	日付 DATE	尺度 SCALE —#—

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本図面は日本モレックス(株)の所有する情報を含むもので 当社の許可なく複製を禁止する。
EN-01C(032)MXJ-32

8 7 6 5 4 3 2 1

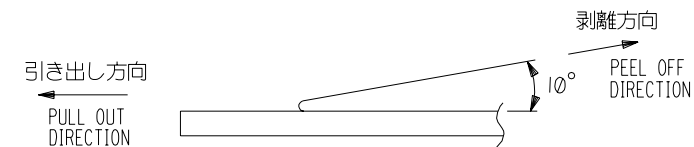
NOTES

1. 梱包数量：1500個/リール
NUMBER OF CONNECTORS : 1500PCS/REEL
2. リードテープ長さ LEAD TAPE LENGTH



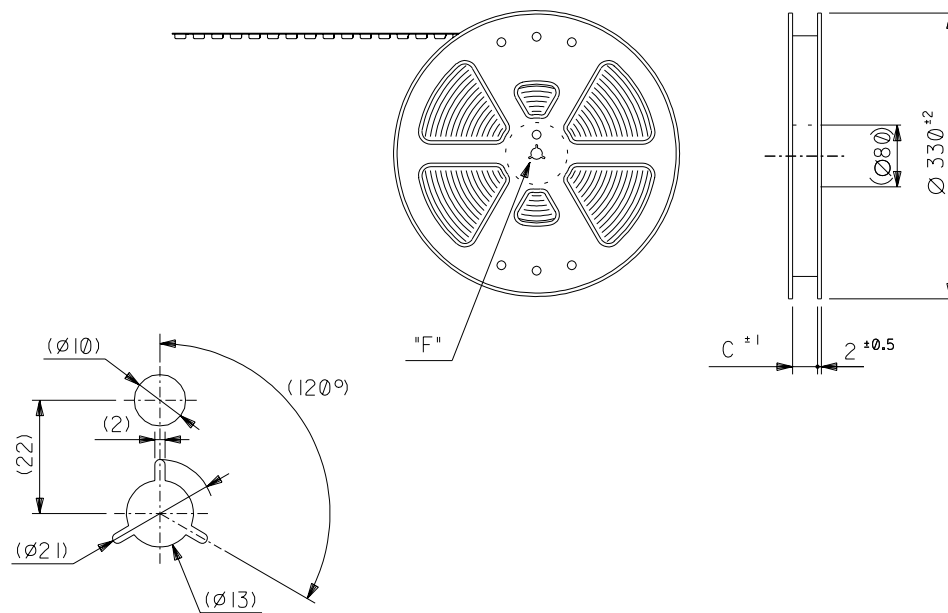
3. トップテープの剥離強度：0.1N ~ 0.7N(10.2gf ~ 71.4gf)
(剥離方向は下図参照)

尚、本規格値は出荷時に適用。(但し、輸送時に剥離が発生しないこと。)
PEELING OFF FORCE OF TOP TAPE : 0.1N ~ 0.7N(10.2gf ~ 71.4gf)
(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
PEEL OFF SHOULD NOT BE ALLOWED , DURING TRANSPORTATION.



4. 材料(MATERIAL)
キャリアテープ(CARRIER TAPE) : ポリプロピレン(POLYPROPYLENE)
トップテープ(TOPTAPE) : PET , PE , PEF
リール(REEL) : ポリスチレン(PS) <リサイクル材を含む>
POLYSTYREN(PS) <RECYCLE MATERIAL CONTAINED>

引き出し方向
PULL OUT DIRECTION



DETAIL "F"

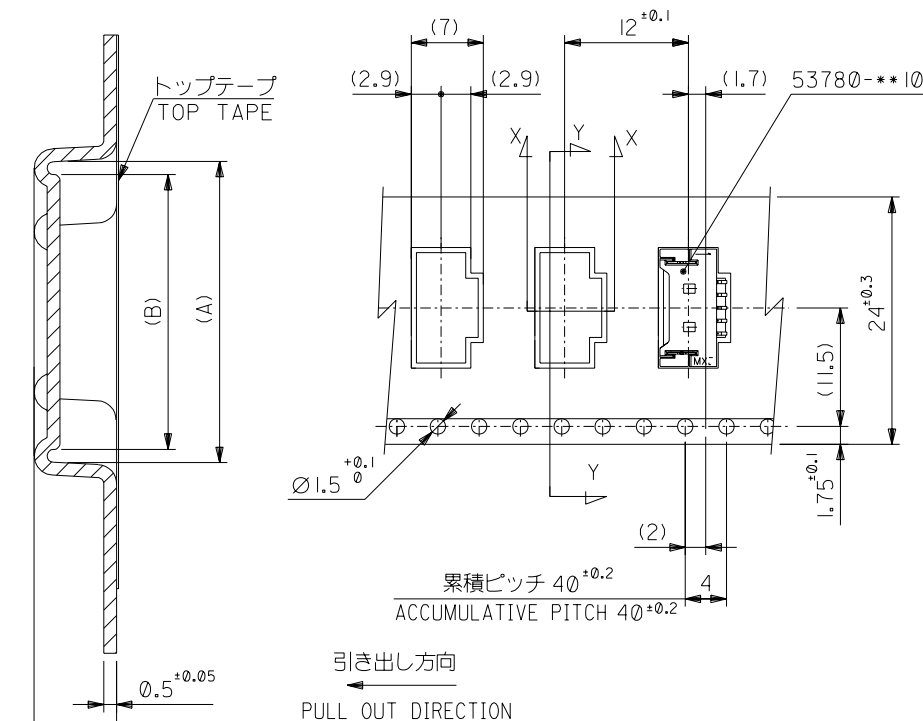
		材料 MATERIAL		注記参照 SEE NOTE	molex MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社
N	変更 REVISED (J2002-2940)	N.I.	K.A.	'02/05/27	REVISE ONLY ON CAD SYSTEM
M	変更 REVISED (JC2001-0424)	K.K.	T.V.	'00/12/6	
L	変更 REVISED (JC2001-0318)	S.M.	T.V.	'00/10/27	TITLE 名称 1.25 W/B WAFER ASS'Y EMBOSSSED TAPE PACKAGE
K	変更 REVISED (JC90327)	S.M.	S.K.	'98/12/1	
J	変更 REVISED (JC80706)	T.A.	S.K.	'98/3/11	DRAWN BY '95/12/27 S.MATSUZAKI CHK'D BY '02/05/27 K.ASAKAWA
H	再作図と変更 REDRAWN & REVISED (JC80662)	T.N.	S.K.	'98/2/20	
一般公差 GENERAL TOLERANCES		記号 LTR	変更内容 REVISION RECORD	DR. 日付 CHK. DATE	DWG. NO. (SHEET 1 OF 3) REV SD-53780-**-90 N

DWG. NO.
SD-53780-**-90

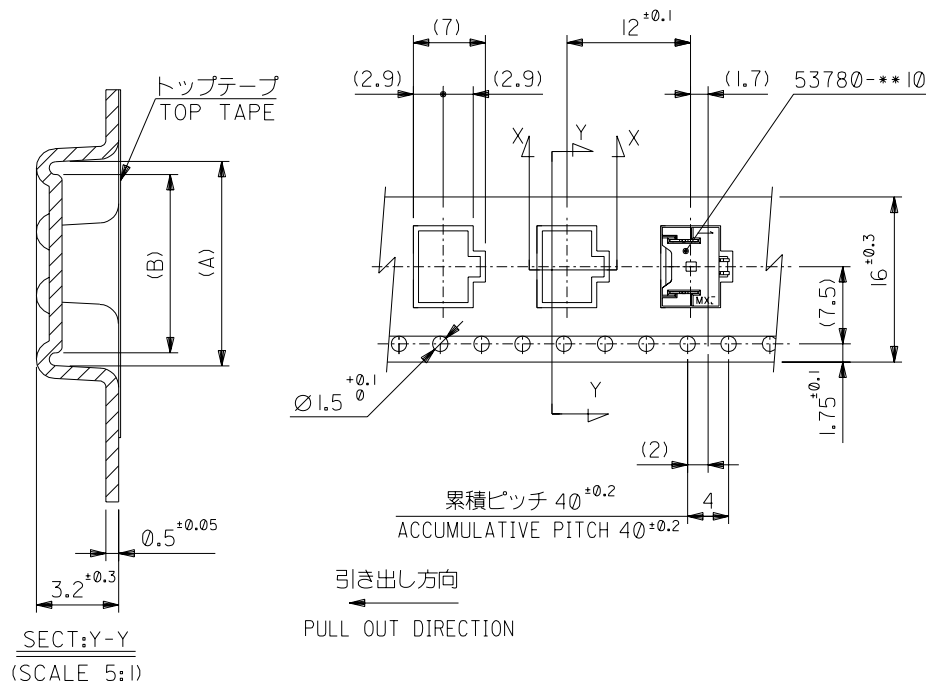
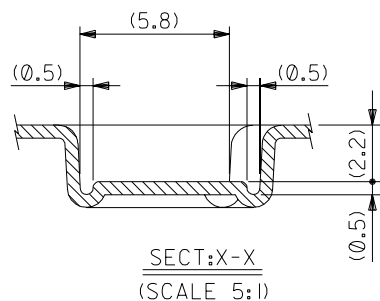
E

D

C
B
A
DIMENSIONS IN METRIC DO NOT SCALE DRAWING



SECT:Y-Y
(SCALE 5:1)



24	25.5	11.75	16.7	53780-0990	9	
		10.5	15.45	53780-0890	8	
		9.25	14.2	53780-0790	7	
		8	12.95	53780-0690	6	
		6.75	11.7	53780-0590	5	
16	17.5	5.5	10.45	53780-0490	4	
		4.25	9.2	53780-0390	3	
		3	7.95	53780-0290	2	
キャリアテープ幅 CARRIER TAPE WIDTH		C	(B)	(A)	ENG. NO.	種数 CKT.

材料 MATERIAL SHEET 1 OF 3 参照 REFER TO SHEET 1 OF 3				molex MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社	
N	変更 REVISED (J2002-2940)	N.I	'02/05/27	仕上げ FINISH	—
M	変更 REVISED (JC2001-0424)	K.K	'00/12/6	適用電線範囲 WIRE RANGE	—
L	変更 REVISED (JC2001-0318)	S.M	'00/10/27	被覆外径 INS. RANGE	—
K	変更 REVISED (JC90327)	S.M	'98/12/1	DRAWN BY '95/12/27 S.MATSUZAKI	CHK'D BY '02/05/27 K.ASAKAWA
J	変更 REVISED (JC80706)	T.A	'98/3/11	APP'D BY '02/05/27 T.YAMAGUCHI	尺度 SCALE —
H	再作図と変更 REDRAWN & REVISED (JC80662)	T.N	'98/2/20	日付 DATE	
記号 LTR	変更内容 REVISION RECORD	DR. CHK.			
角度 ANGLE				DWG. NO. (SHEET 2 OF 3) REV	
30° 以上 OVER				SD-53780-**-90 N	
+0.3					
10° 以上 30° 未満 UNDER					
+0.25					
10° 未満 UNDER					
+0.2					
一般公差 GENERAL TOLERANCES					

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX(JAPAN) AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION
本図面は日本モレックス（株）の所有する情報を含むもので 当社の許可なく複製を禁止する。

EN-01C(032)MXJ-32

DWG. NO. SD-53780-003

F

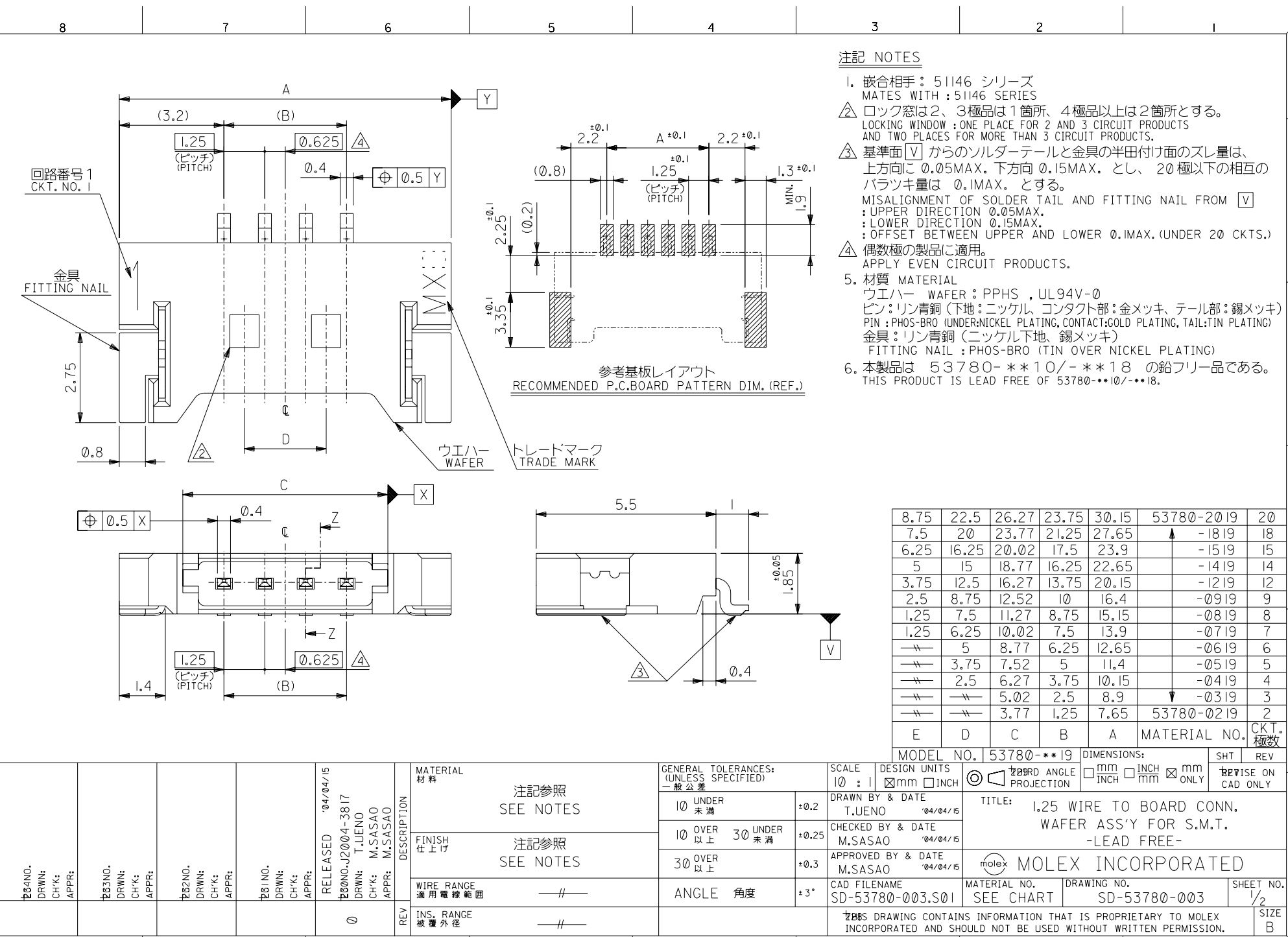
D

V

C

B

DO NOT SCALE DRAWING



注記 NOTES

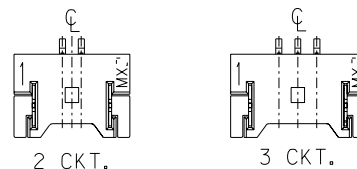
1. 嵌合相手 : 51146 シリーズ
MATES WITH : 51146 SERIES
2. ロック窓は2、3極品は1箇所、4極品以上は2箇所とする。
LOCKING WINDOW : ONE PLACE FOR 2 AND 3 CIRCUIT PRODUCTS
AND TWO PLACES FOR MORE THAN 3 CIRCUIT PRODUCTS.
3. 基準面 [V] からのソルダーテールと金具の半田付け面のズレ量は、
上方向に 0.05MAX. 下方向 0.15MAX. とし、20 極以下の相互の
バラツキ量は 0.1MAX. とする。
MISALIGNMENT OF SOLDER TAIL AND FITTING NAIL FROM [V]
: UPPER DIRECTION 0.05MAX.
: LOWER DIRECTION 0.15MAX.
: OFFSET BETWEEN UPPER AND LOWER 0.1MAX. (UNDER 20 CKTS.)
4. 偶数極の製品に適用。
APPLY EVEN CIRCUIT PRODUCTS.
5. 材質 MATERIAL
ウエハー WAFER : PPHS , UL94V-0
ピン : リン青銅 (下地 : ニッケル、コンタクト部 : 金メッキ、テール部 : 錫メッキ)
PIN : PHOS-BRO (UNDER: NICKEL PLATING, CONTACT: GOLD PLATING, TAIL: TIN PLATING)
金具 : リン青銅 (ニッケル下地、錫メッキ)
FITTING NAIL : PHOS-BRO (TIN OVER NICKEL PLATING)
6. 本製品は 53780- ** 10 / - ** 18 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53780- ** 10 / - ** 18.

8.75	22.5	26.27	23.75	30.15	53780-2019	20
7.5	20	23.77	21.25	27.65	-1819	18
6.25	16.25	20.02	17.5	23.9	-1519	15
5	15	18.77	16.25	22.65	-1419	14
3.75	12.5	16.27	13.75	20.15	-1219	12
2.5	8.75	12.52	10	16.4	-0919	9
1.25	7.5	11.27	8.75	15.15	-0819	8
1.25	6.25	10.02	7.5	13.9	-0719	7
—	5	8.77	6.25	12.65	-0619	6
—	3.75	7.52	5	11.4	-0519	5
—	2.5	6.27	3.75	10.15	-0419	4
—	—	5.02	2.5	8.9	-0319	3
—	—	3.77	1.25	7.65	53780-0219	2
E	D	C	B	A	MATERIAL NO.	CKT. 極数

MODEL NO.	53780- ** 19	DIMENSIONS:	SHT	REV
SCALE	10 : 1	DESIGN UNITS	mm	INCH
GENERAL TOLERANCES:	(UNLESS SPECIFIED)	PROJECTION	mm	INCH
10 UNDER	±0.2	DRAWN BY & DATE	T.JENO	04/04/15
10 OVER	±0.25	CHECKED BY & DATE	M.SASAO	04/04/15
30 OVER	±0.3	APPROVED BY & DATE	M.SASAO	04/04/15
ANGLE	角度	CAD FILENAME	SD-53780-003.S01	
TITLE:		1.25 WIRE TO BOARD CONN. WAFER ASS'Y FOR S.M.T. -LEAD FREE-		
MATERIAL NO.		DRAWING NO.		
SEE CHART		SD-53780-003		
SHEET NO.		1/2		
SIZE		B		

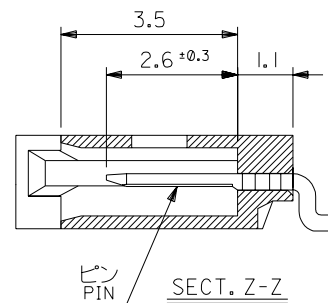
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.

1



ロック形状図

LOCK CONFIGURATION



124 NO. DRWN: CH'K: APPR:		123 NO. DRWN: CH'K: APPR:		122 NO. DRWN: CH'K: APPR:		121 NO. DRWN: CH'K: APPR:		RELEASED 04/04/15 120 NO. J2004-3817 DRWN: T.UENO CH'K: M.SASAO APPR: M.SASAO		DESCRIPTION SEE SHEET 1 OF 2		MATERIAL 材料		GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差		SCALE 10 : 1		MODEL NO.		53780-**-19		DIMENSIONS:		SHT		REV	
												DESIGN UNITS						7890 ANGLE PROJECTION		☐ mm INCH ☐ INCH ☒ mm ONLY		REVISE ON CAD ONLY					
												10 UNDER 未満						±0.2		DRAWN BY & DATE T.UENO '04/04/15		TITLE: 1.25 WIRE TO BOARD CONN. WAFER ASS'Y FOR S.M.T. -LEAD FREE-					
												10 OVER 以上 30 UNDER 未満						±0.25		CHECKED BY & DATE M.SASAO '04/04/15							
												30 OVER 以上		±0.3		APPROVED BY & DATE M.SASAO '04/04/15		MOLEX MOLEX INCORPORATED		CAD FILENAME SD-53780-003.S02		MATERIAL NO.		DRAWING NO.		SHEET NO.	
												ANGLE 角度		±3°		SEE CHART						SD-53780-003		2/2			
8				7				6		0		REV		WIRE RANGE 適用電線範囲		— # —		7890 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.		SIZE B		EN-02J(097) MXJ-54					
														INS. RANGE 被覆外径		— # —											
										5				4		3		2									

DWG. NO. SD-53780-004

F

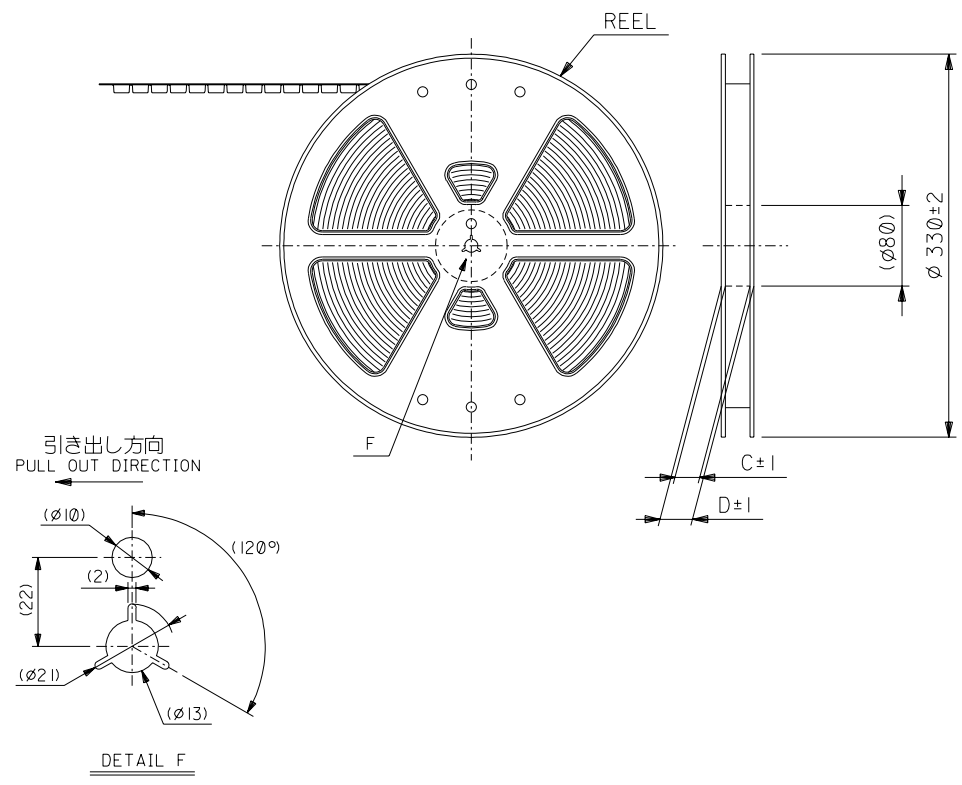
D

C

B

DO NOT SCALE DRAWING

8 7 6 5 4 3 2 1



NOTES

- 梱包数量：1500個/リール
NUMBER OF CONNECTORS : 1500PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH

3. トップテープの剥離強度：0.1N ~ 1.3N(10gf ~ 130gf)
(剥離方向は下図参照)
尚、本規格値は出荷時に適用。(但し、輸送時に剥離が発生しないこと。)
PEELING OFF FORCE OF TOP TAPE : 0.1N ~ 1.3N(10gf ~ 130gf)
(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
PEEL OFF SHOULD NOT BE ALLOWED , DURING TRANSPORTATION.

4. 材料(MATERIAL)
キャリアテープ(CARRIER TAPE)：ポリプロピレン(POLYPROPYLENE)
トップテープ(TOPTAPE)：PET , PE , PEF
リール(REEL)：ポリスチレン(PS) <リサイクル材を含む>
POLYSTYRENE(PS) <RECYCLE MATERIAL CONTAINED>
- 本製品は 53780- **90/- **80 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53780- **90/- **80.

F

E

D

C

B

A

										MODEL NO.		53780-**-70		DIMENSIONS:		SHT	REV				
										DESIGN UNITS		☒ mm ☐ INCH		☐ mm ☐ INCH ☒ mm ONLY		☒ REVERSE ON CAD ONLY					
										SCALE		DRAWN BY & DATE		TITLE: 1.25 W/B WAFER ASS'Y EMBOSSED TAPE PACKAGE -LEAD FREE-							
										GENERAL TOLERANCES: (UNLESS SPECIFIED)		T.UENO '04/04/15									
										10 UNDER 未満		±0.2									
										FINISH 仕上げ		30 OVER 以上 30 UNDER 未満		±0.25		MOLEX MOLEX INCORPORATED					
										WIRE RANGE 適用電線範囲		30 OVER 以上		±0.3							
										ANGLE 角度		CAD FILENAME		MATERIAL NO.		DRAWING NO.		SHEET NO.			
												SD-53780-004.S01		SEE CHART		SD-53780-004		1/3			
												DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.								SIZE B	

8 7 6 5 4 3 2 1 EN-02J(097) MXJ-54

DWG. NO.
SD-53780-004

F

D

V

C

B

DO NOT SCALE DRAWING

8 7 6 5 4 3 2 1

F

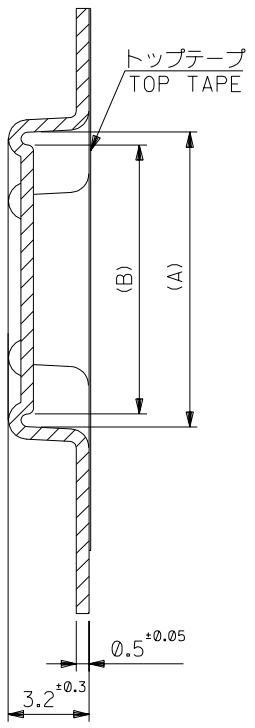
E

D

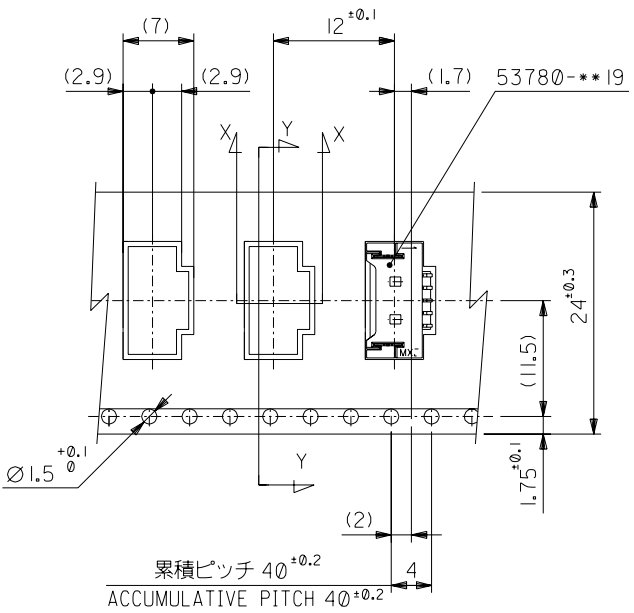
C

B

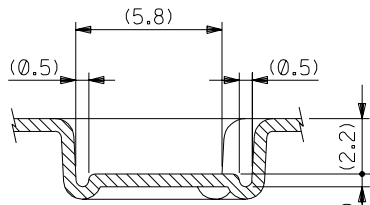
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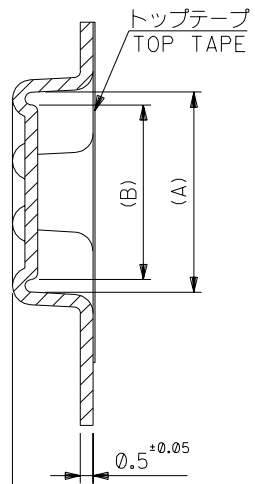
SECT:Y-Y
(SCALE 5:1)



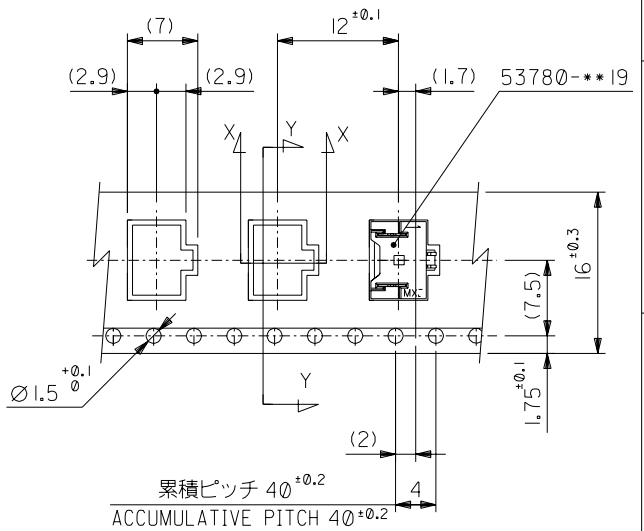
引き出し方向
PULL OUT DIRECTION



SECT:X-X
(SCALE 5:1)



SECT:Y-Y
(SCALE 5:1)



引き出し方向
PULL OUT DIRECTION

24	29.4	25.4	11.75	16.7	53780-0970	9
			10.5	15.45	53780-0870	8
			9.25	14.2	53780-0770	7
			8	12.95	53780-0670	6
			6.75	11.7	53780-0570	5
16	21.4	17.4	5.5	10.45	53780-0470	4
			4.25	9.2	53780-0370	3
			3	7.95	53780-0270	2
キャリアテープ幅 CARRIER TAPE WIDTH	D	C	(B)	(A)	MATERIAL NO.	極致 CKT.

GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差		SCALE 2 : 1	DESIGN UNITS ☒ mm ☐ INCH	 3RD ANGLE PROJECTION	☐ mm ☐ INCH ☐ mm ☐ mm ☒ mm ONLY	SHT REV	22 15 ON CAD ONLY	
10 UNDER 未満	±0.2	DRAWN BY & DATE T.UENO '04/04/15		TITLE: 1.25 W/B WAFER ASS'Y EMBOSSD TAPE PACKAGE -LEAD FREE-				
10 OVER 30 UNDER 以上 未満	±0.25	CHECKED BY & DATE M.SASAO '04/04/15						
30 OVER 以上	±0.3	APPROVED BY & DATE M.SASAO '04/04/15						
ANGLE 角度		±3°	CAD FILENAME SD-53780-004.S02					MATERIAL NO. SEE CHART
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.						SIZE B

8 7 6 5 4 3 2 1

EN-02J(097) MXJ-54

DO NOT SCALE DRAWING

DWG. NO.
SD-53780-004

F

D

C

B

A

8 7 6 5 4 3 2 1

F

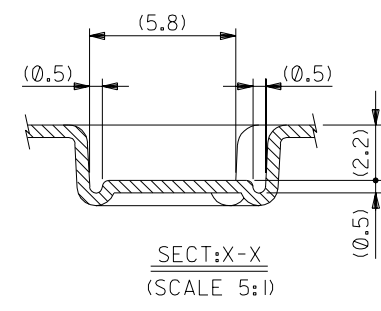
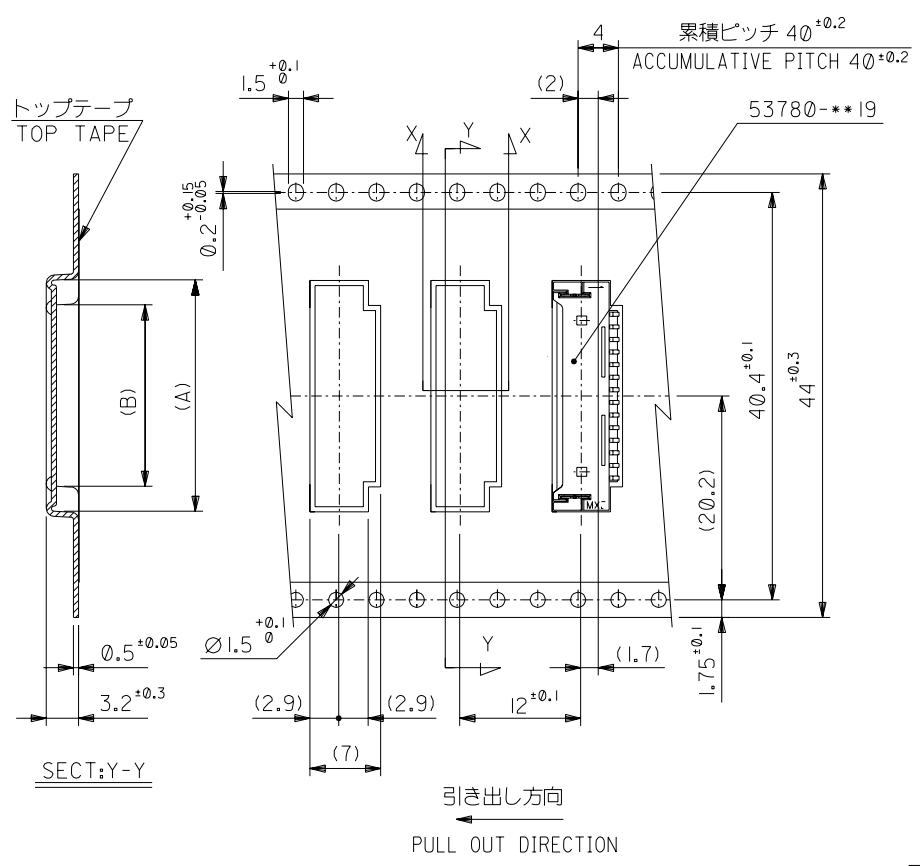
E

D

C

B

A



44		49.4	45.4	25.5	30.45	53780-2070	20	
				25.5	27.95	53780-1870	18	
				19.25	24.2	53780-1570	15	
				18	22.95	53780-1470	14	
				15.5	20.45	53780-1270	12	
キャリアテープ幅 CARRIER TAPE WIDTH		D	C	(B)	(A)	MATERIAL NO.	極数 CKT.	
		MODEL NO.	53780-**-70		DIMENSIONS:		SHT	REV
ANCES: FIED)		SCALE —/—	DESIGN UNITS ☒ mm ☐ INCH	 2-面角 PROJECTION	☐ mm INCH ☐ mm ☒ mm ONLY		2面 ON CAD ONLY	
	±0.2	DRAWN BY & DATE T.UENO '04/04/15		TITLE: 1.25 W/B WAFER ASS'Y EMBOSSD TAPE PACKAGE -LEAD FREE-				
0 UNDER 未満	±0.25	CHECKED BY & DATE M.SASAO '04/04/15						
	±0.3	APPROVED BY & DATE M.SASAO '04/04/15						
角度	±3°	CAD FILENAME SD-53780-004.S03		MOLEX MATERIAL NO.	DRAWING NO. SD-53780-004		SHEET NO. 3/3	
		2面 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.				SIZE B		

164NO. DRWN: CH'K: APPR:	163NO. DRWN: CH'K: APPR:	162NO. DRWN: CH'K: APPR:	161NO. DRWN: CH'K: APPR:	RELEASED '04/04/15 J2004-3817 DRWN: T.UENO CH'K: M.SASAO APPR: M.SASAO	DESCRIPTION REV	MATERIAL 材料 —//—
						FINISH 仕上げ —//—
						WIRE RANGE 適用電線範囲 —//—
						INS. RANGE 被覆外径 —//—

8 7 6 5 4 3 2 1